1 32762 substrate with "GaAs" USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; BM	2003/08/29 08:01 2003/08/29 08:02 2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
2 1 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic near body 2 14 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4 4 1 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic) and base with "CuW" or "Cu/Mo/Cu" 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; IPO; IPO; IPO; IPO; IPO; IPO; IPO; I	2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
2 1 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic near body 2 14 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4 4 1 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base with "CuW" or "Cu/Mo/Cu" 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base with "CuW" or "Cu/Mo/Cu" 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) Wish plastic) and base with "CuW" or "Cu/Mo/Cu" 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) Wish plastic) and base and "CuW" or "Cu/Mo/Cu" 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) Wish plastic) and base and "CuW" or "Cu/Mo/Cu" 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) Wish plastic) and base and "CuW" or "Cu/Mo/Cu" 8 PGPUB; EPO; PO; DERWENT; IBM_TDB 10 USPAT; US-PGPUB; EPO; PO; DERWENT; IBM_TDB 10 USPAT; US-PGPUB; EPO; PO; DERWENT; IBM_TDB 11 USPAT; US-PGPUB; EPO; PO; DERWENT; IBM_TDB 12 USPAT; US-PGPUB; EPO; PO; DERWENT; IBM_TDB	2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
2 1 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic near body 3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic USPAT; US-PGPUB; EPO; PO; DERWENT; IBM_TDB USPAT; US-PGPUB; ISPO; PO; DERWENT; ISM_TDB USPAT; US-PGPUB; ISM_TDB	2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
2	2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
plastic near body During Port Derwent During Port Derwent	2003/08/29 08:04 2003/08/29 08:08 2003/08/29 08:06
214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4	2003/08/29 08:08 2003/08/29 08:06
3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; With plastic) and base with "CuW" or "Cu/Mo/Cu" 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; With plastic) and base with ("CuW" or "Cu/Mo/Cu") 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; With plastic) and base and "CuW" or "Cu/Mo/Cu" 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 10 10 10 10 10 10 10 10 10 10 10 10 10 1	2003/08/29 08:08 2003/08/29 08:06
3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO, JPO, DERWENT; IBM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO, JPO; DERWENT; ISM_	2003/08/29 08:08 2003/08/29 08:06
3 214 (substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic 4 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base with "CuW" or "Cu/Mo/Cu" 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base with ("CuW" or "Cu/Mo/Cu" 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base with ("CuW" or "Cu/Mo/Cu") 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base and "CuW" or "Cu/Mo/Cu" 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base and "CuW" or "Cu/Mo/Cu" 8 PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:08 2003/08/29 08:06
plastic US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EFO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:08 2003/08/29 08:06
EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (UspAT; Us-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (UspAT; Us-PGPUB; EPO; JPO; DERWENT; IBM_TDB (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) (Substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3)	2003/08/29 08:06
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:06
4 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB USPAT; With plastic) and base with ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; BM_TDB 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB 1 USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB 1 USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB 1 USPAT; US-PGPUB; EPO; JPO; DERWENT; BM_TDB	2003/08/29 08:06
41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 5 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base with ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 1 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and ("CuW" or "Cu/Mo/Cu") USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 2 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:06
with plastic) and base with "CuW" or "Cu/Mo/Cu" 4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; with plastic) and base with ("CuW" or "Cu/Mo/Cu") 6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and "CuW" or "Cu/Mo/Cu" 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and ("CuW" or "Cu/Mo/Cu") ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:06
EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; With plastic) and base and "CuW" or "Cu/Mo/Cu" ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) WSPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
DERWENT; IBM_TDB USPAT; With plastic) and base with ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and "CuW" or "Cu/Mo/Cu" ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; With plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
Same to the plastic of the plastic	
4 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; with plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
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6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; with plastic) and base and ("CuW" or "Cu/Mo/Cu") USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:13
6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:13
6 41 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB 7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; With plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:13
with plastic) and base and "CuW" or "Cu/Mo/Cu" US-PGPUB; EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) With plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:13
EPO; JPO; DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic) and base and ("CuW" or "Cu/Mo/Cu") USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
DERWENT; IBM_TDB ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
7 5 ((substrate with "GaAs") and (cover\$3 enclos\$3 cap lid encapsul\$3) USPAT; with plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
with plastic) and base and ("CuW" or "Cu/Mo/Cu") US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
EPO; JPO; DERWENT; IBM_TDB	2003/08/29 08:35
DERWENT; IBM_TDB	
IBM_TDB	
8	2003/08/29 08:36
US-PGPUB;	2003/08/29 08.30
EPO; JPO;	
DERWENT;	
IBM TDB	
9 2 ("5644169").PN. USPAT;	2003/08/29 08:36
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM_TDB	}
- 195411 (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic USPAT;	2003/08/29 08:02
US-PGPUB;	
ЕРО; ЈРО;	
DERWENT;	
IBM_TDB	2002/00/20 00 ==
- 2396 (cover\$3 enclos\$3 cap lid encapsul\$3) with plastic near body USPAT;	2003/08/29 08:01
US-PGPUB;	
EPO; JPO;	
DERWENT;	
IBM TDB	
0 ((cover\$3 enclos\$3 cap lid encapsul\$3) with ((plastic near body) near5 USPAT; (one-piece one?piece one adj piece))) with electric\$4 near3 lead US-PGPUB;	2003/00/20 00:01
(one-piece one?piece one adj piece))) with electric\$4 near3 lead US-PGPUB; EPO; JPO;	2003/08/28 08:01
DERWENT;	2003/08/28 08:01
IBM_TDB	2003/08/28 08:01

-	0	((cover\$3 enclos\$3 cap lid encapsul\$3) with ((plastic near body) near5	USPAT;	2003/08/28 07:52
		(one-piece one?piece one adj piece))) with conduct\$4 near3 lead	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
	82	(cover\$3 enclos\$3 cap lid encapsul\$3) with ((plastic near body) near5	USPAT;	2003/08/28 07:55
		(one-piece one?piece one adj piece))	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	0	((cover\$3 enclos\$3 cap lid encapsul\$3) with ((plastic near body) near5	USPAT;	2003/08/28 07:53
	1	(one-piece one?piece one adj piece))) with lead	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	12	((cover\$3 enclos\$3 cap lid encapsul\$3) with ((plastic near body) near5	USPAT;	2003/08/28 08:44
		(one-piece one?piece one adj piece))) and electrical\$3	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
•	10	((cover\$3 enclos\$3 cap lid encapsul\$3) with plastic near body) with	USPAT;	2003/08/28 09:05
		electric\$4 near3 lead	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	
-	2	("5952714").PN.	USPAT;	2003/08/28 08:45
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
-	2	("5598034").PN.	USPAT;	2003/08/28 14:42
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	•
			IBM_TDB	
-	2	("5097318").PN.	USPAT;	2003/08/28 14:42
			US-PGPUB;	
	1		ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB	